

DUAL-BAND RF SYNTHESIZER WITH INTEGRATED VCOS FOR WIRELESS COMMUNICATIONS

FEATURES

- Dual-band RF synthesizers
 - RF1: 900 MHz to 1.8 GHz
 - RF2: 750 MHz to 1.5 GHz
- IF synthesizer
 - IF: 62.5 to 1000 MHz
- Integrated VCOs, loop filters,
 varactors, and resonators
 varactors
 </
- Low phase noise
 - Programmable powerdown modes
- 1 µA standby current
- 18 mA typical supply current
 - 2.7 to 3.6 V operation
 - Packages: 24-pin TSSOP, 28-lead QFN
 - Minimal (2) number of external Lead-free and RoHS compliant components required

Applications

- Dual-band communications
- Digital cellular telephones GSM 850, E-GSM 900, DCS 1800, PCS 1900
- Digital cordless phones
- Analog cordless phones
- Wireless local loop

Description

The Si4133 is a monolithic integrated circuit that performs both IF and dualband RF synthesis for wireless communications applications. The Si4133 includes three VCOs, loop filters, reference and VCO dividers, and phase detectors. Divider and powerdown settings are programmable with a threewire serial interface.

Functional Block Diagram







Patents pending



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1. Electrical Specifications

Table 1. Recommended Operating Conditions

| Parameter | Symbol | Test Condition | Min | Тур | Max | Unit |
|--|----------------|---|------|-----|-----|------|
| Ambient Temperature | T _A | | -40 | 25 | 85 | °C |
| Supply Voltage | V_{DD} | | 2.7 | 3.0 | 3.6 | V |
| Supply Voltages Difference | V_{Δ} | (V _{DDR} – V _{DDD}), (V _{DDI} – V _{DDD}) | -0.3 | — | 0.3 | V |
| Note: All minimum and maximum specifications are guaranteed and apply across the recommended operating conditions. Typical values apply at nominal supply voltages and an operating temperature of 25 °C unless otherwise stated. | | | | | | |

Table 2. Absolute Maximum Ratings^{1,2}

| Parameter | Symbol | Value | Unit |
|----------------------------|------------------|------------------------------|------|
| DC Supply Voltage | V _{DD} | -0.5 to 4.0 | V |
| Input Current ³ | I _{IN} | ±10 | mA |
| Input Voltage ³ | V _{IN} | –0.3 to V _{DD} +0.3 | V |
| Storage Temperature Range | T _{STG} | –55 to 150 | °C |

Notes:

1. Permanent device damage may occur if the above Absolute Maximum Ratings are exceeded. Functional operation should be restricted to the conditions as specified in the operational sections of this data sheet. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

2. This device is a high performance RF integrated circuit with an ESD rating of < 2 kV. Handling and assembly of this device should only be done at ESD-protected workstations.

3. For signals SCLK, SDATA, SEN, PWDN and XIN.



Table 3. DC Characteristics

 $(V_{DD} = 2.7 \text{ to } 3.6 \text{ V}, \text{ T}_{A} = -40 \text{ to } 85 \text{ °C})$

| Parameter | Symbol | Test Condition | Min | Тур | Max | Unit |
|---|-----------------|---|----------------------|-----|--------------|------|
| Total Supply Current ¹ | | RF1 and IF operating | — | 18 | 27 | mA |
| RF1 Mode Supply Current ¹ | | | | 10 | 16 | mA |
| RF2 Mode Supply Current ¹ | | | | 9 | 16 | mA |
| IF Mode Supply Current ¹ | | | | 8 | 13 | mA |
| Standby Current | | $\overline{PWDN} = 0$ | | 1 | | μA |
| High Level Input Voltage ² | V _{IH} | | $0.7 V_{DD}$ | _ | | V |
| Low Level Input Voltage ² | V _{IL} | | | | $0.3 V_{DD}$ | V |
| High Level Input Current ² | I _{IH} | V _{IH} = 3.6 V, V _{DD} = 3.6 V | -10 | _ | 10 | μA |
| Low Level Input Current ² | I | V _{IL} = 0 V, V _{DD} = 3.6 V | -10 | _ | 10 | μA |
| High Level Output Voltage ³ | V _{OH} | I _{OH} = -500 μA | V _{DD} -0.4 | | | V |
| Low Level Output Voltage ³ | V _{OL} | I _{OH} = 500 μA | | _ | 0.4 | V |
| Notes: 1. RF1 = 1.6 GHz, RF2 = 1.1 GHz, IFOUT = 550 MHz, LPWR = 0. | | | | | | |

For signals SCLK, SDATA, SEN, and PWDN.
 For signal AUXOUT.



Table 4. Serial Interface Timing

 $(V_{DD} = 2.7 \text{ to } 3.6 \text{ V}, \text{ } \text{T}_{\text{A}} = -40 \text{ to } 85 \text{ }^{\circ}\text{C})$

| Symbol | Test Condition | Min | Тур | Max | Unit |
|-------------------|--|--|---|---|---|
| t _{clk} | Figure 1 | 40 | | — | ns |
| t _r | Figure 1 | | | 50 | ns |
| t _f | Figure 1 | | | 50 | ns |
| t _h | Figure 1 | 10 | | | ns |
| t | Figure 1 | 10 | | — | ns |
| t _{su} | Figure 2 | 5 | | | ns |
| t _{hold} | Figure 2 | 0 | | | ns |
| t _{en1} | Figure 2 | 10 | | | ns |
| t _{en2} | Figure 2 | 12 | | _ | ns |
| t _{en3} | Figure 2 | 12 | | | ns |
| t _w | Figure 2 | 10 | | | ns |
| | Symbol t _{clk} t _r t _f t _h t _l t _{su} t _{hold} t _{en1} t _{en3} t _w | SymbolTest Condition t_{olk} Figure 1 t_r Figure 1 t_r Figure 1 t_f Figure 1 t_h Figure 2 t_{su} Figure 2 t_{hold} Figure 2 t_{en1} Figure 2 t_{en3} Figure 2 t_w Figure 2 | SymbolTest ConditionMin t_{clk} Figure 140 t_r Figure 1 t_r Figure 1 t_f Figure 110 t_h Figure 110 t_su Figure 25 t_{hold} Figure 20 t_{en1} Figure 210 t_{en3} Figure 212 t_w Figure 210 | Symbol Test Condition Min Typ t_{clk} Figure 1 40 — t_r Figure 1 — — t_r Figure 1 — — t_f Figure 1 — — t_h Figure 1 10 — t_h Figure 2 5 — t_{su} Figure 2 0 — t_{hold} Figure 2 0 — t_{en1} Figure 2 10 — t_{en2} Figure 2 12 — t_{en3} Figure 2 10 — t_w Figure 2 10 — | Symbol Test Condition Min Typ Max t_{olk} Figure 1 40 t_r Figure 1 50 t_r Figure 1 50 t_f Figure 1 50 t_h Figure 1 10 t_h Figure 2 5 t_{su} Figure 2 0 t_{hold} Figure 2 0 t_{en1} Figure 2 10 t_{en2} Figure 2 12 t_{en3} Figure 2 10 t_w Figure 2 10 |

Notes:

1. All timing is referenced to the 50% level of the waveforms unless otherwise noted.

2. Timing is not referenced to 50% level of the waveform. See Figure 2.



Figure 1. SCLK Timing Diagram





Figure 2. Serial Interface Timing Diagram



Figure 3. Serial Word Format



Table 5. RF and IF Synthesizer Characteristics

 $(V_{DD} = 2.7 \text{ to } 3.6 \text{ V}, \text{ T}_{A} = -40 \text{ to } 85 \text{ }^{\circ}\text{C})$

| Parameter ¹ | Symbol | Test Condition | Min | Тур | Max | Unit |
|--|------------------|------------------------------|-------|------|---------------------------|-------------------|
| XIN Input Frequency | f _{REF} | | 2 | _ | 26 | MHz |
| Reference Amplifier Sensitivity | V _{REF} | | 0.5 | _ | V _{DD} +0.3 V | V _{PP} |
| Phase Detector Update Frequency | f _φ | $f_{\phi} = f_{REF}/R$ | 0.010 | _ | 1.0 | MHz |
| RF1 VCO Center Frequency Range | f _{CEN} | | 947 | _ | 1720 | MHz |
| RF1 VCO Tuning Range ² | | Extended frequency operation | 1850 | | 2050 | MHz |
| RF2 VCO Center Frequency Range | f _{CEN} | | 789 | _ | 1429 | MHz |
| RF Tuning Range from f _{CEN} | | Note: L _{EXT} ±10% | -5 | _ | 5 | % |
| IF VCO Center Frequency Range | f _{CEN} | | 526 | | 952 | MHz |
| IFOUT Tuning Range | | with IFDIV | 62.5 | _ | 1000 | MHz |
| IFOUT Tuning Range from f _{CEN} | | Note: L _{EXT} ±10% | -5 | _ | 5 | % |
| RF1 VCO Pushing | | Open loop | _ | 500 | _ | kHz/V |
| RF2 VCO Pushing | | | — | 400 | — | kHz/V |
| IF VCO Pushing | | | — | 300 | — | kHz/V |
| RF1 VCO Pulling | | VSWR = 2:1, all | _ | 400 | _ | kHz _{PP} |
| RF2 VCO Pulling | | phases, open loop | _ | 300 | _ | kHz _{PP} |
| IF VCO Pulling | | | _ | 100 | _ | kHz _{PP} |
| RF1 Phase Noise | | 1 MHz offset | _ | -132 | _ | dBc/Hz |
| RF1 Integrated Phase Error | | 10 Hz to 100 kHz | _ | 0.9 | _ | degrees rms |
| RF2 Phase Noise | | 1 MHz offset | — | -134 | — | dBc/Hz |
| RF2 Integrated Phase Error | | 10 Hz to 100 kHz | _ | 0.7 | _ | degrees rms |
| IF Phase Noise | | 100 kHz offset | _ | -117 | _ | dBc/Hz |
| IF Integrated Phase Error | | 100 Hz to 100 kHz | - | 0.4 | - | degrees rms |

Notes:

1. f_{ϕ} = 200 kHz, RF1 = 1.6 GHz, RF2 = 1.2 GHz, IFOUT = 550 MHz, LPWR = 0, for all parameters unless otherwise noted.

 Extended frequency operation only. V_{DD} ≥ 3.0 V, QFN only, VCO Tuning Range fixed by directly shorting the RFLA and RFLB pins. See Application Note 41 for more details on the Si4133 extended frequency operation.

3. From powerup request (PWDN[↑] or SEN[↑] during a write of 1 to bits PDIB and PDRB in Register 2) to RF and IF synthesizers ready (settled to within 0.1 ppm frequency error).

From powerdown request (PWDN↓, or SEN↑ during a write of 0 to bits PDIB and PDRB in Register 2) to supply current equal to I_{PWDN}.



Table 5. RF and IF Synthesizer Characteristics (Continued)

(V_{DD} = 2.7 to 3.6 V, $T_A = -40$ to 85 °C)

| Parameter ¹ | Symbol | Test Condition | Min | Тур | Max | Unit |
|---|------------------|--|-----|-------------------|---------------|------|
| RF1 Harmonic Suppression | | Second Harmonic | — | -26 | -20 | dBc |
| RF2 Harmonic Suppression | | | | -26 | -20 | dBc |
| IF Harmonic Suppression | | | | -26 | -20 | dBc |
| RFOUT Power Level | | $Z_L = 50 \Omega$ | -8 | -3 | 1 | dBm |
| RFOUT Power Level ² | | $Z_L = 50 \Omega$, RF1 active, Extended frequency operation | -14 | -7 | 1 | dBm |
| IFOUT Power Level | | Z _L = 50 Ω | -8 | -4 | 0 | dBm |
| RF1 Output Reference Spurs | | Offset = 200 kHz | | -65 | | dBc |
| | | Offset = 400 kHz | | -71 | — | dBc |
| | | Offset = 600 kHz | — | -75 | — | dBc |
| RF2 Output Reference Spurs | | Offset = 200 kHz | — | -65 | — | dBc |
| | | Offset = 400 kHz | — | -71 | — | dBc |
| | | Offset = 600 kHz | | -75 | _ | dBc |
| Powerup Request to Synthesizer Ready ³ Time | t _{pup} | Figures 4, 5 | | 40/f _φ | $50/f_{\phi}$ | |
| Powerdown Request to Synthesizer Off ⁴ Time | t _{pdn} | Figures 4, 5 | | | 100 | ns |

Notes:

f_φ = 200 kHz, RF1 = 1.6 GHz, RF2 = 1.2 GHz, IFOUT = 550 MHz, LPWR = 0, for all parameters unless otherwise noted.
 Extended frequency operation only. V_{DD} ≥ 3.0 V, QFN only, VCO Tuning Range fixed by directly shorting the RFLA and RFLB pins. See Application Note 41 for more details on the Si4133 extended frequency operation.

3. From powerup request (PWDN[↑] or SEN[↑] during a write of 1 to bits PDIB and PDRB in Register 2) to RF and IF synthesizers ready (settled to within 0.1 ppm frequency error).

4. From powerdown request (PWDN↓, or SEN↑ during a write of 0 to bits PDIB and PDRB in Register 2) to supply current equal to I_{PWDN}.





Figure 4. Software Power Management Timing Diagram



Figure 5. Hardware Power Management Timing Diagram





Figure 6. Typical Transient Response RF1 at 1.6 GHz with 200 kHz Phase Detector Update Frequency









Figure 8. Typical RF1 Spurious Response at 1.6 GHz with 200 kHz Phase Detector Update Frequency









Figure 10. Typical RF2 Spurious Response at 1.2 GHz with 200 kHz Phase Detector Update Frequency









Figure 12. IF Spurious Response at 550 MHz with 200 kHz Phase Detector Update Frequency









3. Functional Description

The Si4133 is a monolithic integrated circuit that performs IF and dual-band RF synthesis for wireless communications applications. This integrated circuit (IC), with minimal external components, completes the frequency synthesis function necessary for RF communications systems.

The Si4133 has three complete phase-locked loops (PLLs) with integrated voltage-controlled oscillators (VCOs). The low phase noise of the VCOs makes the Si4133 suitable for demanding wireless communications applications. Phase detectors, loop filters, and reference and output frequency dividers are integrated. The IC is programmed with a three-wire serial interface.

Two PLLs are provided for dual-band RF synthesis. These RF PLLs are multiplexed so that only one PLL is active at a time, as determined by the setting of an internal register. The active PLL is the last one to be written. The center frequency of the VCO in each PLL is set by the value of an external inductance. Inaccuracies in these inductances are compensated for by the selftuning algorithm. The algorithm is run after powerup or after a change in the programmed output frequency.

Each RF PLL, when active, can adjust the RF output frequency by $\pm 5\%$ of its VCO's center frequency. Because the two VCOs can be set to have widely separated center frequencies, the RF output can be programmed to service two widely separated frequency bands by programming the corresponding N-Divider. One RF VCO is optimized to have its center frequency set between 947 MHz and 1.72 GHz, while the second RF VCO is optimized to have its center frequency set between 789 MHz and 1.429 GHz.

One PLL is provided for IF frequency synthesis. The center frequency of this circuit's VCO is set by the connection of an external inductance. The PLL can adjust the IF output frequency by $\pm 5\%$ of the VCO center frequency. Inaccuracies in the value of the external inductance are compensated for by the Si4133's proprietary self-tuning algorithm. This algorithm is initiated each time the PLL is powered-up (by either the PWDN pin or by software) and/or each time a new output frequency is programmed.

The IF VCO can have its center frequency set as low as 526 MHz and as high as 952 MHz. An IF output divider divides down the IF output frequencies, if needed. The divider is programmable and is capable of dividing by 1, 2, 4, or 8.

The unique PLL architecture used in the Si4133 produces settling (lock) times that are comparable in speed to fractional-N architectures without the high phase noise or spurious modulation effects often associated with those designs.

3.1. Serial Interface

A timing diagram for the serial interface is shown in Figure 2 on page 7. Figure 3 on page 7 shows the format of the serial word.

The Si4133 is programmed serially with 22-bit words comprised of 18-bit data fields and 4-bit address fields. When the serial interface is enabled (i.e., when SEN is low) data and address bits on the SDATA pin are clocked into an internal shift register on the rising edge of SCLK. Data in the shift register is then transferred on the rising edge of SEN into the internal data register addressed in the address field. The serial interface is disabled when SEN is high.

Table 12 on page 21 summarizes the data register functions and addresses. The internal shift register ignores leading bits before the 22 required bits.

3.2. Setting the VCO Center Frequencies

The PLLs can adjust the IF and RF output frequencies $\pm 5\%$ of the center frequencies of their VCOs. Each center frequency is established by the value of an external inductance connected to the respective VCO. Manufacturing tolerances of $\pm 10\%$ for the external inductances are acceptable. The Si4133 compensates for inaccuracies in each inductance by executing a self-tuning algorithm after PLL powerup or after a change in the programmed output frequency.

Because the total tank inductance is in the low nH range, the inductance of the package must be considered when determining the correct external inductance. The total inductance (L_{TOT}) presented to each VCO is the sum of the external inductance (L_{EXT}) and the package inductance (L_{PKG}). Each VCO has a nominal capacitance (C_{NOM}) in parallel with the total inductance, and the center frequency is as follows:

or

$$f_{CEN} = \frac{1}{2\pi \sqrt{L_{TOT} \times C_{NOM}}}$$

1

$$f_{CEN} = \frac{1}{2\pi \sqrt{(L_{PKG} + L_{EXT}) \times C_{NOM}}}$$

Tables 6 and 7 summarize the characteristics of each VCO.



Table 6. Si4133-GT VCO Characteristics

| vco | f _{CEN} Range (MHz) | | C _{NOM} (pF) | L _{PKG} (nH) | L _{EXT} F (n | Range H) |
|-----|---------------------------------|------|--------------------------|--------------------------|--------------------------|-------------|
| | Min | Max | | | Min | Max |
| RF1 | 947 | 1720 | 4.3 | 2.0 | 0.0 | 4.6 |
| RF2 | 789 | 1429 | 4.8 | 2.3 | 0.3 | 6.2 |
| IF | 526 | 952 | 6.5 | 2.1 | 2.2 | 12.0 |

Table 7. Si4133-GM VCO Characteristics

| vco | f _{CEN} Range (MHz) | | C _{NOM} (pF) | L _{PKG} (nH) | L _{EXT} F (n | Range H) |
|-----|---------------------------------|------|--------------------------|--------------------------|--------------------------|-------------|
| | Min | Max | | | Min | Max |
| RF1 | 947 | 1720 | 4.3 | 1.5 | 0.5 | 5.1 |
| RF2 | 789 | 1429 | 4.8 | 1.5 | 1.1 | 7.0 |
| IF | 526 | 952 | 6.5 | 1.6 | 2.7 | 12.5 |



Figure 15. External Inductance Connection

As a design example, consider that the goal is to synthesize frequencies in a 25 MHz band between 1120 and 1145 MHz using the Si4133-GT. The center frequency should be defined as midway between the two extremes, or 1132.5 MHz. The PLL can adjust the VCO output frequency \pm 5% of the center frequency, or \pm 56.6 MHz of 1132.5 MHz (i.e., from approximately 1076 to 1189 MHz). The RF2 VCO has a C_{NOM} of 4.8 pF. A 4.1 nH inductance in parallel with this capacitance yields the required center frequency. An external inductance of 1.8 nH should be connected between RFLC and RFLD as shown in Figure 15. This, in addition to 2.3 nH of package inductance, presents

the correct total inductance to the VCO. In manufacturing, the external inductance can vary $\pm 10\%$ of its nominal value and the Si4133 corrects for the variation with the self-tuning algorithm.

For more information on designing the external trace inductors, refer to Application Note 31: Inductor Design for the Si41xx Synthesizer Family.

3.3. Extended Frequency Operation

The Si4133 may operate at an extended frequency range of 1850 MHz to 2050 MHz by connecting the RFLA and RFLB pins directly. For information on configuring the Si4133 for extended frequency operation, refer to Application Note 41: Extended Frequency Operation of Silicon Laboratories Frequency Synthesizers.

3.4. Self-Tuning Algorithm

The self-tuning algorithm is initiated immediately after powerup of a PLL or, if the PLL is already powered, after a change in its programmed output frequency. This algorithm attempts to tune the VCO so that its freerunning frequency is near the required output frequency. In doing so, the algorithm compensates for manufacturing tolerance errors in the value of the external inductance connected to the VCO. It also reduces the frequency error for which the PLL must correct to get the precise required output frequency. The self-tuning algorithm leaves the VCO oscillating at a frequency in error by somewhat less than 1% of the desired output frequency.

After self-tuning, the PLL controls the VCO oscillation frequency. The PLL completes frequency locking, eliminating any remaining frequency error. From then on, it maintains frequency-lock, compensating for effects of temperature and supply voltage variations.

The Si4133's self-tuning algorithm compensates for component value errors at any temperature within the specified temperature range. However, the ability of the PLL to compensate for drift in component values that occur after self-tuning is limited. For external inductances with temperature coefficients approximately \pm 150 ppm/°C, the PLL can maintain lock for changes in temperature of approximately \pm 30 °C.

Applications where the PLL is regularly powered down or the frequency is periodically reprogrammed minimize or eliminate the potential effects of temperature drift because the VCO is re-tuned in either case. In applications where the ambient temperature can drift substantially after self-tuning, it might be necessary to monitor the lock-detect bar (LDETB) signal on the AUXOUT pin to determine whether a PLL is about to run out of locking capability. See "3.10. Auxiliary Output



(AUXOUT)" for how to select LDETB. The LDETB signal is low after self-tuning is completed but rises when the IF or RF PLL nears the limit of its compensation range. LDETB is also high when either PLL is executing the self-tuning algorithm. The output frequency is still locked when LDETB goes high, but the PLL eventually loses lock if the temperature continues to drift in the same direction. Therefore, if LDETB goes high both the IF and RF PLLs should be re-tuned promptly by initiating the self-tuning algorithm.

3.5. Output Frequencies

The IF and RF output frequencies are set by programming the R- and N-Divider registers. Each PLL has R and N registers so that each can be programmed independently. Programming either the R- or N-Divider register for RF1 or RF2 automatically selects the associated output.

The reference frequency on the XIN pin is divided by R and this signal is input to the PLL's phase detector. The other input to the phase detector is the PLL's VCO output frequency divided by N. The PLL acts to make these frequencies equal.

That is, after an initial transient:

or

$$f_{OUT} = \frac{N}{R} \times f_{REF}$$

 $\frac{f_{OUT}}{N} = \frac{f_{REF}}{R}$

The R values are set by programming the RF1 R-Divider register (Register 6), the RF2 R-Divider register (Register 7) and the IF R-Divider register (Register 8).

The N values are set by programming the RF1 N-Divider register (Register 3), the RF2 N-Divider register (Register 4), and the IF N-Divider register (Register 5).

Each N-Divider is implemented as a conventional high speed divider. That is, it consists of a dual-modulus prescaler, a swallow counter, and a lower speed synchronous counter. However, the control of these sub-circuits is automatically handled. Only the appropriate N value should be programmed.

3.6. PLL Loop Dynamics

The transient response for each PLL is determined by its phase detector update rate f_{φ} (equal to f_{REF}/R) and the phase detector gain programmed for each RF1, RF2, or IF synthesizer. See Register 1. Four different settings for the phase detector gain are available for each PLL. The highest gain is programmed by setting the two phase detector gain bits to 00, and the lowest by

setting the bits to 11. The values of the available gains, relative to the highest gain, are as follows:

Table 8. Gain Values (Register 1)

| K _P Bits | Relative P.D. Gain |
|---------------------|-----------------------|
| 00 | 1 |
| 01 | 1/2 |
| 10 | 1/4 |
| 11 | 1/8 |

The gain value bits is automatically set with the Auto K_P bit (bit 2) in the Main Configuration register to 1. In setting this bit, the gain values are optimized for a given value of N. In general, a higher phase detector gain decreases in-band phase noise and increase the speed of the PLL transient until the point at which stability begins to be compromised. The optimal gain depends on N. Table 9 lists recommended settings for different values of N. These are the settings when the Auto K_P bit is set.

Table 9. Optimal K_P Settings

| N | RF1 K _{P1} <1:0> | RF2 K _{P2} <3:2> | IF K _{PI} <5:4> |
|----------------|------------------------------|------------------------------|-----------------------------|
| ≤2047 | 00 | 00 | 00 |
| 2048 to 4095 | 00 | 00 | 01 |
| 4096 to 8191 | 00 | 01 | 10 |
| 8192 to 16383 | 01 | 10 | 11 |
| 16384 to 32767 | 10 | 11 | 11 |
| ≥32768 | 11 | 11 | 11 |

The VCO gain and loop filter characteristics are not programmable.

The settling time for the PLL is directly proportional to its phase detector update period T_{φ} (T_{φ} equals $1/f_{\varphi}$). A typical transient response is shown in Figure 6 on page 11. During the first 13 update periods the Si4133 executes the self-tuning algorithm. From then on the PLL controls the output frequency. Because of the unique architecture of the Si4133 PLLs, the time required to settle the output frequency to 0.1 ppm error is automatically 25 update periods. The total time after powerup or a change in programmed frequency until the synthesized frequency is settled—including time for self-tuning—is approximately 40 update periods.

Note: The settling time analysis holds for RF1 $f_{\varphi} \le 500$ kHz. For RF1 $f_{\varphi} > 500$ kHz, the settling time is larger.



3.7. RF and IF Outputs

The RFOUT and IFOUT pins are driven by amplifiers that buffer the RF VCOs and IF VCO respectively. The RF output amplifier receives its input from the RF1 or RF2 VCO, depending on which R- or N-Divider register is written last. For example, programming the N-Divider register for RF1 automatically selects the RF1 VCO output.

Figures 13 and 14 show application diagrams for the Si4133. The RF output signal must be ac coupled to its load through a capacitor. An external inductance between the RFOUT pin and the ac coupling capacitor is required as part of an output matching network to maximize power delivered to the load. This 2 nH inductance can be realized with a PC board trace. The network is made to provide an adequate match to an external 50 Ω load for both the RF1 and RF2 frequency bands. The matching network also filters the output signal to reduce harmonic distortion.

The IFOUT pin must also be ac coupled to its load through a capacitor. The IF output level is dependent upon the load. Figure 18 on page 20 displays the output level versus load resistance for a variety of output frequencies. For resistive loads greater than 500 Ω the output level saturates and the bias currents in the IF output amplifier are higher than required. The LPWR bit in the Main Configuration register (Register 0) can be set to 1 to reduce the bias currents and therefore reduce the power dissipated by the IF amplifier. For loads less than 500 Ω , LPWR should be set to 0 to maximize the output level.

For IF frequencies greater than 500 MHz, a matching network is required to drive a 50 Ω load. See Figure 16. The value of L_{MATCH} can be determined from Table 10.

| Frequency | LMATCH |
|---------------|--------|
| 500–600 MHz | 40 nH |
| 600–800 MHz | 27 nH |
| 800 MHz–1 GHz | 18 nH |

Table 10. L_{MATCH} Values







For frequencies less than 500 MHz, the IF output buffer can directly drive a 200 Ω resistive load or higher. For resistive loads greater than 500 Ω (f < 500 MHz) the LPWR bit can be set to reduce the power consumed by the IF output buffer. See Figure 17.



Figure 17. IF Frequencies < 500 MHz

3.8. Reference Frequency Amplifier

The Si4133 provides a reference frequency amplifier. If the driving signal has CMOS levels it can be connected directly to the XIN pin. Otherwise, the reference frequency signal should be ac coupled to the XIN pin through a 560 pF capacitor.

3.9. Powerdown Modes

Table 11 summarizes the powerdown functionality. The Si4133 can be powered down by taking the PWDN pin low or by setting bits in the Powerdown register (Register 2). When the PWDN pin is low, the Si4133 is powered down regardless of the Powerdown register settings. When the PWDN pin is high, power management is in control of the Powerdown register bits.

The IF and RF sections of the Si4133 circuitry can be individually powered down by setting the Powerdown register bits PDIB and PDRB low, respectively. The reference frequency amplifier is also powered up if the PDRB and PDIB bits are high. Also, setting the AUTOPDB bit to 1 in the Main Configuration register (Register 0) is equivalent to setting both bits in the Powerdown register to 1.

The serial interface remains available and can be written in all powerdown modes.

3.10. Auxiliary Output (AUXOUT)

The signal appearing on AUXOUT is selected by setting the AUXSEL bits in the Main Configuration register (Register 0).

The LDETB signal can be selected by setting the AUXSEL bits to 11. This signal can be used to indicate that the IF or RF PLL is going to lose lock because of excessive ambient temperature drift and should be re-tuned. The LDETB signal indicates a logical OR result if both IF and RF are simultaneously generating a signal.

| PWDN Pin | AUTOPDB | PDIB | PDRB | IF Circuitry | RF Circuitry |
|-----------------------|---------|------|------|--------------|---------------------|
| $\overline{PWDN} = 0$ | Х | Х | Х | OFF | OFF |
| | 0 | 0 | 0 | OFF | OFF |
| | 0 | 0 | 1 | OFF | ON |
| PWDN = 1 | 0 | 1 | 0 | ON | OFF |
| | 0 | 1 | 1 | ON | ON |
| | 1 | x | х | ON | ON |

Table 11. Powerdown Configuration



Figure 18. Typical IF Output Voltage vs. Load Resistance at 550 MHz



4. Control Registers

| Register | Name | Bit 17 | Bit 16 | Bit 15 | Bit 14 | Bit 13 | Bit 12 | Bit 11 | Bit 10 | Bit 9 | Bit 8 | Bit 7 | Bit 6 | Bit 5 | Bit 4 | Bit 3 | Bit 2 | Bit 1 | Bit 0 |
|----------|----------------------------|---|-----------|-----------|-----------|------------|------------|------------|------------|----------|----------|----------|-----------------|-----------------------|----------|-----------------|------------------------|-----------------|----------|
| 0 | Main Configura- tion | 0 | 0 | 0 | 0 | AUX [1: | SEL :0] | IFC [1: | DIV :0] | 0 | 0 | 0 | 0 | LPWR | 0 | AUTO PDB | AUTO K _P | RF PWR | 0 |
| 1 | Phase Detector Gain | 0 | 0 | 0 | 0 | 0 | 0 | 0 | 0 | 0 | 0 | 0 | 0 | K _{PI} [| [1:0] | K _{P2} | [1:0] | K _{P1} | [1:0] |
| 2 | Powerdown | 0 | 0 | 0 | 0 | 0 | 0 | 0 | 0 | 0 | 0 | 0 | 0 | 0 | 0 | 0 | 0 | PDIB | PDRB |
| 3 | RF1 N-Divider | | | | | | | | | N | RF1[| 17:0] | | | | | | | |
| 4 | RF2 N-Divider | 0 N _{RF2} [16:0] 0 0 N _{IF} [15:0] | | | | | | | | | | | | | | | | | |
| 5 | IF N-Divider | 0 0 N _{IF} [15:0] | | | | | | | | | | | | | | | | | |
| 6 | RF1 R-Divider | 0 | 0 | 0 | 0 | 0 | | | | | | | R _{RF} | : ₁ [12:0] | | | | | |
| 7 | RF2 R-Divider | 0 | 0 | 0 | 0 | 0 | | | | | | | R _{RF} | : ₂ [12:0] | | | | | |
| 8 | IF R-Divider | 0 | 0 | 0 | 0 | 0 | | | | | | | R _{IF} | [12:0] | | | | | |
| 9 | Reserved | | | | | | | | | | | | | | | | | | |
| | | | | | | | | | | | | | | | | | | | |
| 15 | Reserved | | | | | | | | | | | | | | | | | | |

Table 12. Register Summary

Note: Registers 9–15 are reserved. Writes to these registers might result in unpredictable behavior. Registers not listed here are reserved and should not be written.



Register 0. Main Configuration Address Field = A[3:0] = 0000

| Bit | D17 | D16 | D15 | D14 | D13 | D12 | D11 | D10 | D9 | D8 | D7 | D6 | D5 | D4 | D3 | D2 | D1 | D0 |
|-------|-----|-----|------|-----------------|------------|------------------------------|--|--|--------------------------------------|--------------------------------------|----------------------------------|--------------------------------|-------------------------------|-------------------|-------------|------------------------|-----------|-------|
| Name | 0 | 0 | 0 | 0 | AUX [1: | SEL 0] | IF[[1 | DIV :0] | 0 | 0 | 0 | 0 | LPWR | 0 | AUTO PDB | AUTO K _P | RF PWR | 0 |
| Bit | | | Na | me | | | | | | | | Fund | tion | | | | | |
| 17:14 | 1 | | Rese | erved | | Pro | gram | to zero |) . | | | | | | | | | |
| 13:12 | 2 | , | AUXS | EL[1:0 |] | Au 00 01 10 11 : | xiliary = Res = Forc = Res = Lock | Outp erved. ce outp erved. c Detec | ut Pir out lov ct—Ll | n Def w. DETB | initio | n. | | | | | | |
| 11:10 |) | | IFDI | V[1:0] | | IF (00 01 10 11 | Dutpu = IFOI = IFOI = IFOI = IFOI | t Divid UT = II UT = II UT = II UT = II | der. FVCC FVCC FVCC FVCC |) Fred) Fred) Fred) Fred | quenc quenc quenc quenc | cy cy/2 cy/4 cy/8 | | | | | | |
| 9:6 | | | Rese | erved | | Pro | gram | to zero | Э. | | | | | | | | | |
| 5 | | | LP | WR | | Ou 0 = 1 = | t put P R _{LOA} R _{LOA} | °ower- _D < 50 _D ≥ 50 | Leve 0 Ω— 0 Ω— | I Sett -norm -low p | i ngs al po ower | f or If wer n mod | F Syntl node. e. | hesize | er Circ | uit. | | |
| 4 | | | Rese | erved | | Pro | gram | to zero | Э. | | | | | | | | | |
| 3 | | | AUT | OPDB | | Au 0 = 1 = | t o Pov Softw Equiv | verdo vare po valent t | wn. werd o set | own i ting a | s con Il bits | trolle in Re | d by Ro egister | egistei 2 = 1. | r 2. | | | |
| 2 | | | AUT | ОК _Р | | Au 0 = 1 = | t o K_P K _P s a K _P s a | Settin are cor are set | g. itrolle acco | d by l rding | Regis to Ta | ter 1. ble 9 | on pag | je 18. | | | | |
| 1 | | | RFF | PWR | | Pro mo | gram re info | to zero rmatio | o. (Us m.) | ed fo | r exte | ended | freque | ency o | peratic | on. See | e AN4 | 1 for |
| 0 | | | Rese | erved | | Pro | gram | to zero | Э. | | | | | | | | | |



| Bit | D17 | D16 | D15 | D14 | D13 | D12 | D11 | D10 | D9 | D8 | D7 | D6 | D5 | D4 | D3 | D2 | D1 | D0 |
|------|--------|--------|-----------------|--------|---------|--|---|---------------------------|--|-------------------|-------|--------|-------------------|--------|-----------------|-------|-----------------|-------|
| Name | 0 | 0 | 0 | 0 | 0 | 0 | 0 | 0 | 0 | 0 | 0 | 0 | K _{PI} [| 1:0] | K _{P2} | [1:0] | K _{P1} | [1:0] |
| Bit | | | Na | me | | | | | | | F | uncti | on | | | | | |
| 17:6 | | | Rese | erved | | Pro | gram | to zer | 0. | | | | | | | | | |
| 5:4 | | | K _{PI} | [1:0] | | IF F N V <20 204 409 | Phase /alue)48 8–409 6–819 | Dete 95 91 | ctor G K _{Pl} = 00 = 01 = 10 = 11 | ain C | onsta | ant.* | | | | | | |
| 3:2 | | | K _{P2} | [1:0] | | RF2 N V <40 409 819 >16 | 2 Pha /alue)96 -819)2–163)383 | se De 91 383 | tector $K_{P2} = 00$ = 01 = 10 = 11 | [.] Gain | Cons | stant. | * | | | | | |
| 1:0 | Vhen A | AUTOK | K _{P1} | [1:0] | bits do | RF ⁻ N V <81 819 163 >32 not ne | 1 Pha /alue 92–163 884–32 2767 ed to b | se De 383 2767 | tector K _{P1} = 00 = 01 = 10 = 11 | Gain | en AU | stant. | * = 0. us | e thes | e reco | mmeno | ded va | lues |
| fo | r prog | rammir | ng Pha | se Det | ector C | Gain. | | ,o pi0g | | | | ιοιφ | – 0, 03 | 0 1100 | | | 100 10 | 1000 |

Register 1. Phase Detector Gain Address Field (A[3:0]) = 0001



| Bit | D17 | D16 | D15 | D14 | D13 | D12 | D11 | D10 | D9 | D8 | D7 | D6 | D5 | D4 | D3 | D2 | D1 | D0 |
|---------|--------|---------|--------|---------|--------|--------------------|--------------------------|-------------------------------|--------------------------|------------------------|--------------------------|-------------------|-------|-------|----|----|------|------|
| Name | 0 | 0 | 0 | 0 | 0 | 0 | 0 | 0 | 0 | 0 | 0 | 0 | 0 | 0 | 0 | 0 | PDIB | PDRB |
| Bit | | | N | ame | | | 1 | | | | | Fur | ction | | | | | |
| 17:2 | | | Res | servec | | Р | rograr | n to z | ero. | | | | | | | | | |
| 1 | | | Ρ | DIB | | P 0 1 | ower = IF s = IF s | down synthe synthe | IF Sy sizer sizer | nthes powe on. | sizer. red do | own. | | | | | | |
| 0 | | | PI | DRB | | P 0 1 | ower = RF = RF | down synth synth | RF S esizei esizei | ynthe powe r on. | e sizer ered c | . lown. | | | | | | |
| Note: E | nablin | g any l | PLL wi | ith PDI | B or P | DRB | automa | atically | powe | rs on t | he refe | erence | ampli | fier. | | | | |

Register 2. Powerdown Address Field (A[3:0]) = 0010

Register 3. RF1 N-Divider Address Field (A[3:0]) = 0011

| Bit | D17 | D16 | D15 | D14 | D13 | D12 | D11 | D10 | D9 | D8 | D7 | D6 | D5 | D4 | D3 | D2 | D1 | D0 |
|------|-----|--------------------|-------|-----|--------|--------|-------|--------|------------------|--------|--------|-----|----|----|----|----|----|----|
| Name | | | | | | | | | N _{RF1} | [17:0] | | | | | | | | |
| Bit | | Nar | ne | | | | | | | F | Functi | ion | | | | | | |
| 17:0 | | N _{RF1} [| 17:0] | N-I | Divide | er for | RF1 S | Synthe | sizer. | | | | | | | | | |

Register 4. RF2 N-Divider Address Field = A[3:0] = 0100

| Bit | D17 | D16 | D15 | D14 | D13 | D12 | D11 | D10 | D9 | D8 | D7 | D6 | D5 | D4 | D3 | D2 | D1 | D0 |
|------|-----|-----|-----|-----|-----|-----|-----|-----|----|--------------------|-------|----|----|----|----|----|----|----|
| Name | 0 | | | | | | | | N | _{RF2} [16 | :0] | | | | | | | |
| Bit | | Nam | ne | | | | | | | F | uncti | on | | | | | | |

| 17 | Reserved | Program to zero. |
|------|-------------------------|--------------------------------|
| 16:0 | N _{RF2} [16:0] | N-Divider for RF2 Synthesizer. |



| Register 5 | . IF | N-Divider | Address | Field | (A[3:0]) | = 0101 |
|-------------------|------|------------------|---------|-------|----------|--------|
|-------------------|------|------------------|---------|-------|----------|--------|

| Bit | D17 | D16 | D15 | D14 | D13 | D12 | D11 | D10 | D9 | D8 | D7 | D6 | D5 | D4 | D3 | D2 | D1 | D0 |
|-------|-----|-----|-------------------|-------|-----|-----|--------|---------|-------|--------------------|-------|-------|----|----|----|----|----|----|
| Name | 0 | 0 | | | | | | | | N _{IF} [′ | 15:0] | | | | | | | • |
| Bit | | | Na | me | | | | | | | F | uncti | on | | | | | |
| 17:16 | 6 | | Rese | erved | | Pro | gram | to zer | 0. | | | | | | | | | |
| 15:0 | | | N _{IF} [| 15:0] | | N-D | Divide | r for l | F Syn | thesi | zer. | | | | | | | |

| Register 6. RF1 R-Divider Address Field (A[3:0]) = 011 | Register | 6. RF1 | R-Divider | Address Field | d (A[3:0]) | = 0110 |
|---|----------|--------|------------------|---------------|------------|--------|
|---|----------|--------|------------------|---------------|------------|--------|

| Bit | D17 | D16 | D15 | D14 | D13 | D12 | D11 | D10 | D9 | D8 | D7 | D6 | D5 | D4 | D3 | D2 | D1 | D0 |
|-------|-----|-----------------|---------|-----|------------------|--------|-------|-------|--------|---------|---------|---------------------|-----|----|----|----|----|----|
| Name | 0 | 0 | 0 | 0 | 0 | | | 1 | | | R | _{RF1} [12 | :0] | | | 1 | | 1 |
| | | N | lame | | | | | | | | Fund | tion | | | | | | |
| 17:13 | 3 | Re | serve | b | Progra | am to | zero. | | | | | | | | | | | |
| 12:0 |) | R _{RI} | F1[12:0 |)] | R-Div | ider f | or RF | 1 Syn | thesiz | zer. | | | | | | | | |
| | | | | | R _{RF1} | can be | e any | value | from 7 | ' to 81 | 89 if k | (_{P1} = 0 | 00 | | | | | |
| | | | | | | | | | 8 | 8 to 81 | 89 if k | (_{P1} = 0 | 01 | | | | | |
| | | | | | | | | | 10 |) to 81 | 89 if k | κ _{P1} = ' | 10 | | | | | |
| | | | | | | | | | 14 | l to 81 | 89 if k | (_{P1} = 1 | 11 | | | | | |

Register 7. RF2 R-Divider Address Field (A[3:0]) = 0111

| Bit | D17 | D16 | D15 | D14 | D13 | D12 | D11 | D10 | D9 | D8 | D7 | D6 | D5 | D4 | D3 | D2 | D1 | D0 |
|------|-----|-----|-----|-----|-----|-----|-----|-----|----|----|----|--------------------|-----|----|----|----|----|----|
| Name | 0 | 0 | 0 | 0 | 0 | | | | | | R | _{RF2} [12 | :0] | | | | | |

| Bit | Name | Function |
|-------|-------------------------|--|
| 17:13 | Reserved | Program to zero. |
| 12:0 | R _{RF2} [12:0] | R-Divider for RF2 Synthesizer. |
| | | R_{RF2} can be any value from 7 to 8189 if $K_{P2} = 00$ |
| | | 8 to 8189 if K _{P2} = 01 |
| | | 10 to 8189 if K _{P2} = 10 |
| | | 14 to 8189 if K _{P2} = 11 |



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Register 8. IF R-Divider Address Field (A[3:0]) = 1000

| | - | - | | | - | - | | | | - | - | - | - | | | | - | |
|-------|-----|-----|--------|-----|-----------------------------------|------------------------------------|--------|---------|-------|--------|--------|-----------------------|----|----|----|----|----|----|
| Bit | D17 | D16 | D15 | D14 | D13 | D12 | D11 | D10 | D9 | D8 | D7 | D6 | D5 | D4 | D3 | D2 | D1 | D0 |
| Name | 0 | 0 | 0 | 0 | 0 | | • | • | | | F | R _{IF} [12:0 | D] | | • | • | | |
| Bit | | ١ | lame | | | Function | | | | | | | | | | | | |
| 17:13 | 3 | Re | serve | d | Prog | ram to | zero. | i. | | | | | | | | | | |
| 12:0 |) | R | F[12:0 |] | R-Div | vider | for IF | Synth | esize | er. | | | | | | | | |
| | | | | | R _{IF} c | an be | any v | alue fr | om | 7 to 8 | 189 if | K _{P1} = | 00 | | | | | |
| | | | | | 8 to 8189 if K _{P1} = 01 | | | | | | | | | | | | | |
| | | | | | | 10 to 8189 if K _{P1} = 10 | | | | | | | | | | | | |
| | | | | | | 14 to 8189 if K _{P1} = 11 | | | | | | | | | | | | |



5. Pin Descriptions: Si4133-GT



| Pin Number | Name | Description |
|------------|--------|--|
| 1 | SCLK | Serial clock input |
| 2 | SDATA | Serial data input |
| 3 | GNDR | Common ground for RF analog circuitry |
| 4 | RFLD | Pins for inductor connection to RF2 VCO |
| 5 | RFLC | Pins for inductor connection to RF2 VCO |
| 6 | GNDR | Common ground for RF analog circuitry |
| 7 | RFLB | Pins for inductor connection to RF1 VCO |
| 8 | RFLA | Pins for inductor connection to RF1 VCO |
| 9 | GNDR | Common ground for RF analog circuitry |
| 10 | GNDR | Common ground for RF analog circuitry |
| 11 | RFOUT | Radio frequency (RF) output of the selected RF VCO |
| 12 | VDDR | Supply voltage for the RF analog circuitry |
| 13 | AUXOUT | Auxiliary output |
| 14 | PWDN | Powerdown input pin |
| 15 | XIN | Reference frequency amplifier input |
| 16 | GNDD | Common ground for digital circuitry |
| 17 | VDDD | Supply voltage for digital circuitry |
| 18 | GNDD | Common ground for digital circuitry |
| 19 | IFLA | Pins for inductor connection to IF VCO |
| 20 | IFLB | Pins for inductor connection to IF VCO |
| 21 | GNDI | Common ground for IF analog circuitry |
| 22 | IFOUT | Intermediate frequency (IF) output of the IF VCO |
| 23 | VDDI | Supply voltage for IF analog circuitry |
| 24 | SEN | Enable serial port input |



| Pin Number | Si4133 | Si4123 | Si4122 | Si4113 | Si4112 |
|------------|--------|--------|--------|--------|--------|
| 1 | SCLK | SCLK | SCLK | SCLK | SCLK |
| 2 | SDATA | SDATA | SDATA | SDATA | SDATA |
| 3 | GNDR | GNDR | GNDR | GNDR | GNDD |
| 4 | RFLD | GNDR | RFLD | RFLD | GNDD |
| 5 | RFLC | GNDR | RFLC | RFLC | GNDD |
| 6 | GNDR | GNDR | GNDR | GNDR | GNDD |
| 7 | RFLB | RFLB | GNDR | RFLB | GNDD |
| 8 | RFLA | RFLA | GNDR | RFLA | GNDD |
| 9 | GNDR | GNDR | GNDR | GNDR | GNDD |
| 10 | GNDR | GNDR | GNDR | GNDR | GNDD |
| 11 | RFOUT | RFOUT | RFOUT | RFOUT | GNDD |
| 12 | VDDR | VDDR | VDDR | VDDR | VDDD |
| 13 | AUXOUT | AUXOUT | AUXOUT | AUXOUT | AUXOUT |
| 14 | PWDN | PWDN | PWDN | PWDN | PWDN |
| 15 | XIN | XIN | XIN | XIN | XIN |
| 16 | GNDD | GNDD | GNDD | GNDD | GNDD |
| 17 | VDDD | VDDD | VDDD | VDDD | VDDD |
| 18 | GNDD | GNDD | GNDD | GNDD | GNDD |
| 19 | IFLA | IFLA | IFLA | GNDD | IFLA |
| 20 | IFLB | IFLB | IFLB | GNDD | IFLB |
| 21 | GNDI | GNDI | GNDI | GNDD | GNDI |
| 22 | IFOUT | IFOUT | IFOUT | GNDD | IFOUT |
| 23 | VDDI | VDDI | VDDI | VDDD | VDDI |
| 24 | SEN | SEN | SEN | SEN | SEN |

Table 13. Pin Descriptions for Si4133 Derivatives—TSSOP



6. Pin Descriptions: Si4133-GM



| Pin Number | Name | Description |
|------------|--------|--|
| 1 | GNDR | Common ground for RF analog circuitry |
| 2 | RFLD | Pins for inductor connection to RF2 VCO |
| 3 | RFLC | Pins for inductor connection to RF2 VCO |
| 4 | GNDR | Common ground for RF analog circuitry |
| 5 | RFLB | Pins for inductor connection to RF1 VCO |
| 6 | RFLA | Pins for inductor connection to RF1 VCO |
| 7 | GNDR | Common ground for RF analog circuitry |
| 8 | GNDR | Common ground for RF analog circuitry |
| 9 | GNDR | Common ground for RF analog circuitry |
| 10 | RFOUT | Radio frequency (RF) output of the selected RF VCO |
| 11 | VDDR | Supply voltage for the RF analog circuitry |
| 12 | AUXOUT | Auxiliary output |
| 13 | PWDN | Powerdown input pin |
| 14 | GNDD | Common ground for digital circuitry |
| 15 | XIN | Reference frequency amplifier input |
| 16 | GNDD | Common ground for digital circuitry |
| 17 | VDDD | Supply voltage for digital circuitry |
| 18 | GNDD | Common ground for digital circuitry |
| 19 | IFLA | Pins for inductor connection to IF VCO |
| 20 | IFLB | Pins for inductor connection to IF VCO |
| 21 | GNDI | Common ground for IF analog circuitry |
| 22 | GNDI | Common ground for IF analog circuitry |
| 23 | IFOUT | Intermediate frequency (IF) output of the IF VCO |
| 24 | VDDI | Supply voltage for IF analog circuitry |
| 25 | SEN | Enable serial port input |
| 26 | SCLK | Serial clock input |
| 27 | SDATA | Serial data input |
| 28 | GNDR | Common ground for RF analog circuitry |



| Pin Number | Si4133 | Si4123 | Si4122 | Si4113 | Si4112 |
|------------|--------|--------|--------|--------|--------|
| 1 | GNDR | GNDR | GNDR | GNDR | GNDD |
| 2 | RFLD | GNDR | RFLD | RFLD | GNDD |
| 3 | RFLC | GNDR | RFLC | RFLC | GNDD |
| 4 | GNDR | GNDR | GNDR | GNDR | GNDD |
| 5 | RFLB | RFLB | GNDR | RFLB | GNDD |
| 6 | RFLA | RFLA | GNDR | RFLA | GNDD |
| 7 | GNDR | GNDR | GNDR | GNDR | GNDD |
| 8 | GNDR | GNDR | GNDR | GNDR | GNDD |
| 9 | GNDR | GNDR | GNDR | GNDR | GNDD |
| 10 | RFOUT | RFOUT | RFOUT | RFOUT | GNDD |
| 11 | VDDR | VDDR | VDDR | VDDR | VDDD |
| 12 | AUXOUT | AUXOUT | AUXOUT | AUXOUT | AUXOUT |
| 13 | PWDN | PWDN | PWDN | PWDN | PWDN |
| 14 | GNDD | GNDD | GNDD | GNDD | GNDD |
| 15 | XIN | XIN | XIN | XIN | XIN |
| 16 | GNDD | GNDD | GNDD | GNDD | GNDD |
| 17 | VDDD | VDDD | VDDD | VDDD | VDDD |
| 18 | GNDD | GNDD | GNDD | GNDD | GNDD |
| 19 | IFLA | IFLA | IFLA | GNDD | IFLA |
| 20 | IFLB | IFLB | IFLB | GNDD | IFLB |
| 21 | GNDI | GNDI | GNDI | GNDD | GNDI |
| 22 | GNDI | GNDI | GNDI | GNDD | GNDI |
| 23 | IFOUT | IFOUT | IFOUT | GNDD | IFOUT |
| 24 | VDDI | VDDI | VDDI | VDDD | VDDI |
| 25 | SEN | SEN | SEN | SEN | SEN |
| 26 | SCLK | SCLK | SCLK | SCLK | SCLK |
| 27 | SDATA | SDATA | SDATA | SDATA | SDATA |
| 28 | GNDR | GNDR | GNDR | GNDR | GNDD |

 Table 14. Pin Descriptions for Si4133 Derivatives—QFN



7. Ordering Guide

| Ordering Part Number | Description | Operating Temperature |
|-------------------------|----------------------------------|-----------------------|
| Si4133-D-GM | RF1/RF2/IF OUT, Lead Free, QFN | –40 to 85 °C |
| Si4133-D-GT | RF1/RF2/IF OUT, Lead Free, TSSOP | –40 to 85 °C |
| Si4123-D-GM | RF1/IF OUT, Lead Free, QFN | –40 to 85 °C |
| Si4123-D-GT | RF1/IF OUT, Lead Free, TSSOP | –40 to 85 °C |
| Si4122-D-GM | RF2/IF OUT, Lead Free, QFN | −40 to 85 °C |
| Si4122-D-GT | RF2/IF OUT, Lead Free, TSSOP | –40 to 85 °C |
| Si4113-D-GM | RF1/RF2 OUT, Lead Free, QFN | –40 to 85 °C |
| Si4113-D-GT | RF1/RF2 OUT, Lead Free, TSSOP | −40 to 85 °C |
| Si4113-D-ZT1 | RF1/RF2 OUT, NiPd, TSSOP | −40 to 85 °C |
| Si4112-D-GM | IF OUT, Lead Free, QFN | –40 to 85 °C |
| Si4112-D-GT | IF OUT, Lead Free, TSSOP | −40 to 85 °C |

8. Si4133 Derivative Devices

The Si4133 performs both IF and dual-band RF frequency synthesis. The Si4112, Si4113, Si4122, and the Si4123 are derivatives of this device. Table 15 outlines which synthesizers each derivative device features and the pins and registers that coincide with each synthesizer.

| Table | 15. | Si4133 | Derivatives |
|-------|-----|--------|-------------|
|-------|-----|--------|-------------|

| Name | Synthesizer | Pins | Registers |
|--------|--------------|---------------------------------------|--|
| Si4112 | IF | IFLA, IFLB | N_{IF} , R_{IF} , PDIB, IFDIV, LPWR, AUTOPDB = 0, PDRB = 0 |
| Si4113 | RF1, RF2 | RFLA, RFLB, RFLC, RFLD | N_{RF1} , N_{RF2} , R_{RF1} , R_{RF2} , PDRB, AUTOPDB = 0, PDIB = 0 |
| Si4122 | RF2, IF | RFLC, RFLD, IFLA, IFLB | N _{RF2} , R _{RF2} , PDRB, N _{IF} , R _{IF} , PDIB, IFDIV, LPWR |
| Si4123 | RF1, IF | RFLA, RFLB, IFLA, IFLB | N _{RF1} , R _{RF1} , PDRB, N _{IF} , R _{IF} , PDIB, IFDIV, LPWR |
| Si4133 | RF1, RF2, IF | RFLA, RFLB, RFLC, RFLD, IFLA, IFLB | N _{RF1} , N _{RF2} , R _{RF1} , R _{RF2} , PDRB, N _{IF} , R _{IF} , PDIB, IFDIV, LPWR |



9. Package Outline: Si4133-GT

Figure 19 illustrates the package details for the Si4133-GT. Table 16 lists the values for the dimensions shown in the illustration.



Figure 19. 24-Pin Thin Shrink Small Outline Package (TSSOP)

| Symbol | | Millimeters | | | | |
|--------|------|-------------|------|--|--|--|
| | Min | Nom | Max | | | |
| А | | | 1.20 | | | |
| A1 | 0.05 | | 0.15 | | | |
| b | 0.19 | — | 0.30 | | | |
| С | 0.09 | — | 0.20 | | | |
| D | 7.70 | 7.80 | 7.90 | | | |
| е | | 0.65 BSC | | | | |
| E | | 6.40 BSC | | | | |
| E1 | 4.30 | 4.40 | 4.50 | | | |
| L | 0.45 | 0.60 | 0.75 | | | |
| θ1 | 0° | — | 8° | | | |
| bbb | 0.10 | | | | | |
| ddd | 0.20 | | | | | |

Table 16. Package Diagram Dimensions



10. Package Outline: Si4133-GM

Figure 20 illustrates the package details for the Si4133-GM. Table 17 lists the values for the dimensions shown in the illustration.





| Symbol | Millimeters | | | | | | | |
|--------|-------------|----------|------|--|--|--|--|--|
| | Min | Nom | Max | | | | | |
| Α | 0.80 | 0.85 | 0.90 | | | | | |
| A1 | 0.00 | 0.01 | 0.05 | | | | | |
| b | 0.18 | 0.23 | 0.30 | | | | | |
| D, E | | 5.00 BSC | | | | | | |
| е | 0.50 BSC | | | | | | | |
| D2, E2 | 2.55 | 2.70 | 2.85 | | | | | |

Table 17. Package Dimensions

| Symbol | Millimeters | | |
|--------|-------------|------|------|
| | Min | Nom | Max |
| L | 0.50 | 0.60 | 0.70 |
| aaa | _ | | 0.10 |
| bbb | _ | | 0.10 |
| CCC | _ | | 0.05 |
| ddd | _ | | 0.10 |
| Θ | | — | 12° |

Notes:

1. Dimensioning and tolerancing per ANSI Y14.5M-1994.

2. This package outline conforms to JEDEC MS-220, variant VHHD-1.

3. Recommended card reflow profile is per the JEDEC/IPC J-STD-020B specification for Small Body Components.



DOCUMENT CHANGE LIST

Revision 1.4 to Revision 1.5

- "7.Ordering Guide" on page 31 updated.
- Changed MLP to QFN (same package, generic name)

Revision 1.5 to Revision 1.6

• Updated "7.Ordering Guide" on page 31.

Revision 1.6 to Revision 1.61

Updated contact information.



NOTES:





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